

US Application No 10/826,091  
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**Amendment to the abstract:**

The abstract has been rewritten to comply with MPEP § 608.01(b).

**Abstract:**

An aqueous copper-to-resin bonding layer solution comprising: (a) at least one acid type; (b) tin salt or tin oxide; (c) salt or oxide of at least one type of metal selected from the group consisting of: silver, zinc, aluminum, titanium, bismuth, chromium, iron, cobalt, nickel, palladium, gold, and platinum; (d) a reaction accelerator; and (e) a diffusive retaining solvent, so that an alloy layer of tin and the at least one type of metal selected in (c) is formed on the surface of the copper. Subsequently, a portion of the alloy layer is removed, so that a bonding layer containing an alloy of diffused copper, tin, and the at least one type of metal selected in (c) is formed on a surface of copper which enhances the adhesion between copper and resin. The present invention provides the solution, a method of producing the bonding layer, and a product obtained thereby.